

**TLRE50T,TLRME50T,TLSE50T,TLOE50T,TLYE50T,
TLPYE50T,TLGE50T,TLFGE50T,TLPGE50T**

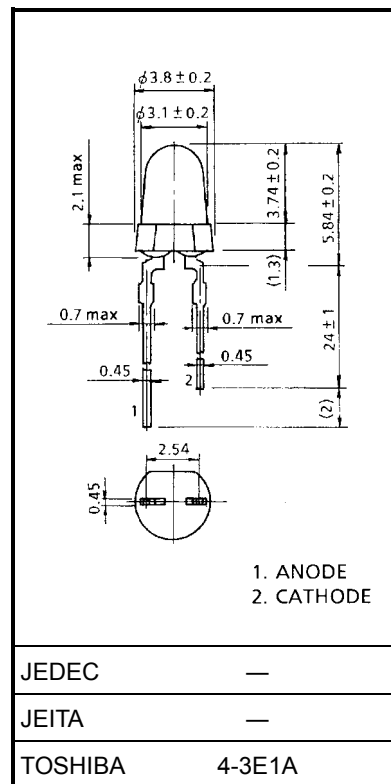
Panel Circuit Indicators

- $\varnothing 3$ mm package
- InGaAlP technology
- All plastic mold type
- Transparent lens
- Line-up: 6 colors (red, orange, yellow, pure yellow, green and pure green)
- High intensity light emission
- Excellent low current light output
- Applications: message boards, security devices and dashboard displays

Line-up

Product Name	Color	Material
TLRE50T	Red	InGaAsP
TLRME50T	Red	
TLSE50T	Red	
TLOE50T	Orange	
TLYE50T	Yellow	
TLPYE50T	Pure Yellow	
TLGE50T	Green	
TLFGE50T	Green	
TLPGE50T	Pure Green	

Unit: mm



Weight: 0.14 g

Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA)	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operating Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLRE50T	50	4	120	-40~100	-40~120
TLRME50T	50	4	120		
TLSE50T	50	4	120		
TLOE50T	50	4	120		
TLYE50T	50	4	120		
TLPYE50T	50	4	120		
TLGE50T	50	4	120		
TLFGE50T	50	4	120		
TLPGE50T	50	4	120		

Electrical and Optical Characteristics (Ta = 25°C)

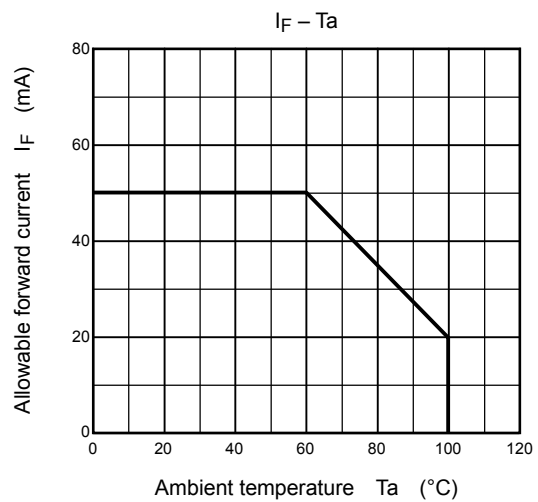
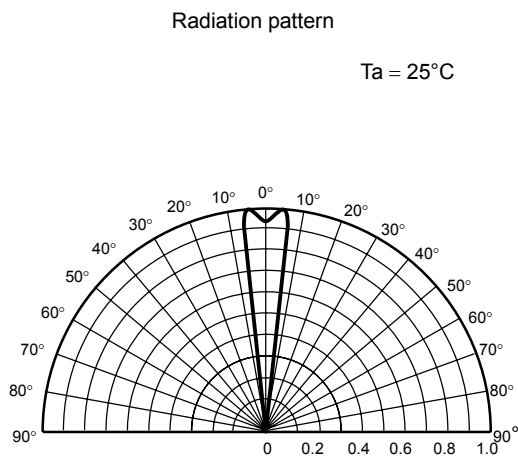
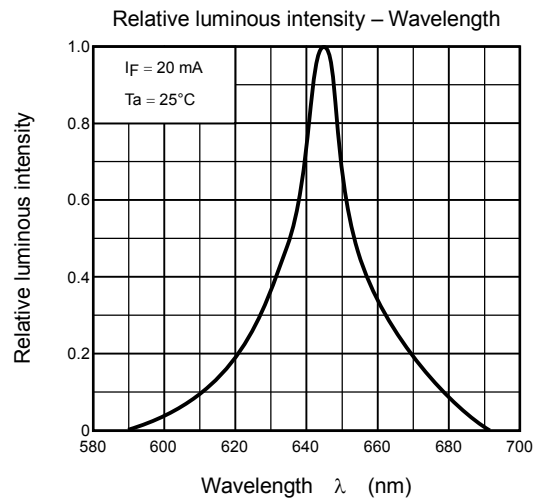
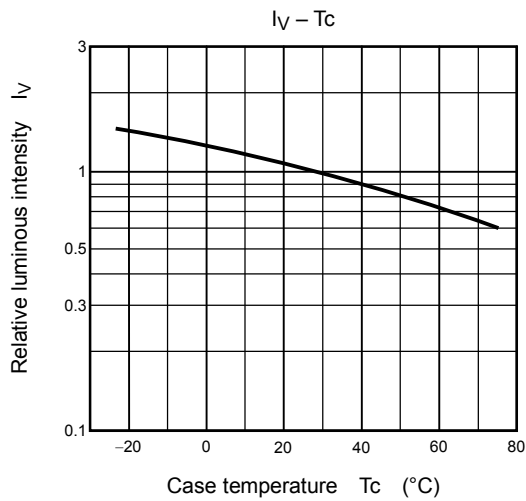
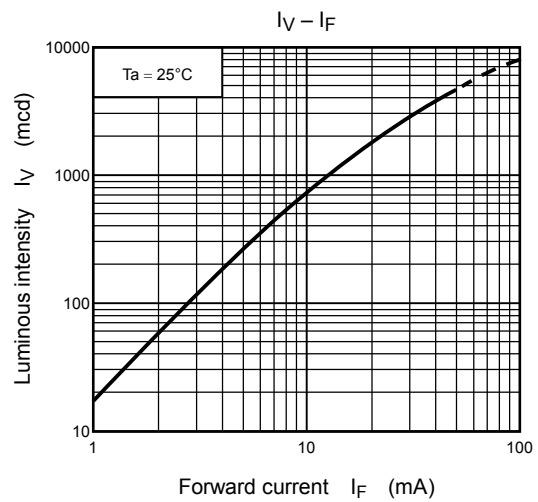
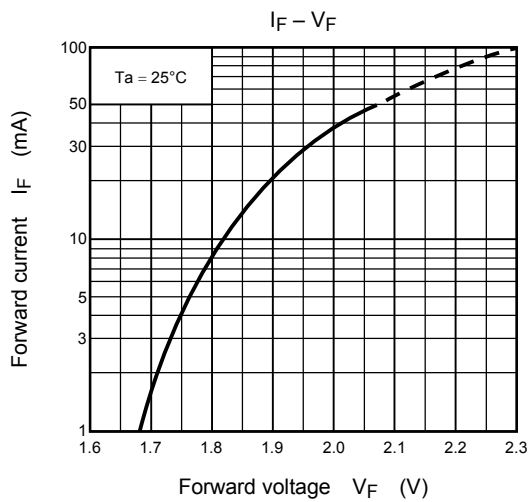
Product Name	Typ. Emission Wavelength				Luminous Intensity I _V			Forward Voltage V _F			Reverse Current I _R	
	λ _d	λ _P	Δλ	I _F	Min	Typ.	I _F	Typ.	Max	I _F	Max	V _R
TLRE50T	630	(644)	20	20	850	1800	20	1.9	2.4	20	50	4
TLRME50T	626	(636)	23	20	850	2200	20	1.9	2.4	20	50	4
TLSE50T	613	(623)	20	20	1530	3500	20	1.9	2.4	20	50	4
TLOE50T	605	(612)	20	20	1530	4500	20	2.0	2.4	20	50	4
TLYE50T	587	(590)	17	20	1530	3500	20	2.0	2.4	20	50	4
TLPYE50T	580	(583)	14	20	850	2500	20	2.0	2.4	20	50	4
TLGE50T	571	(574)	17	20	476	1500	20	2.0	2.4	20	50	4
TLFGE50T	565	(568)	15	20	272	1000	20	2.0	2.4	20	50	4
TLPGE50T	558	(562)	14	20	153	600	20	2.1	2.4	20	50	4
Unit	nm			mA	mcd		mA	V		mA	μA	V

Precautions

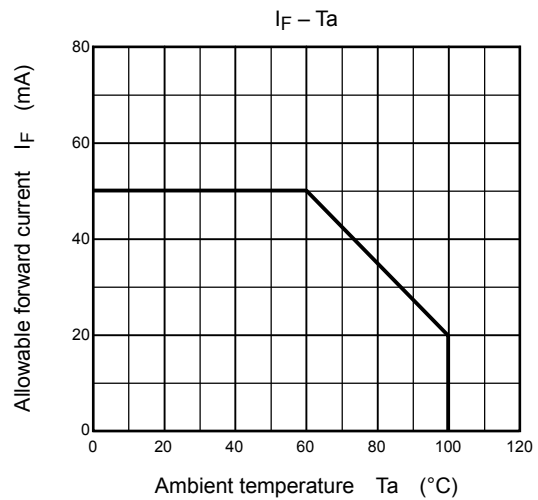
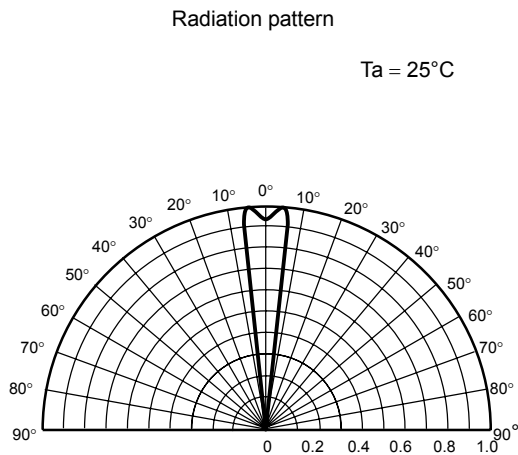
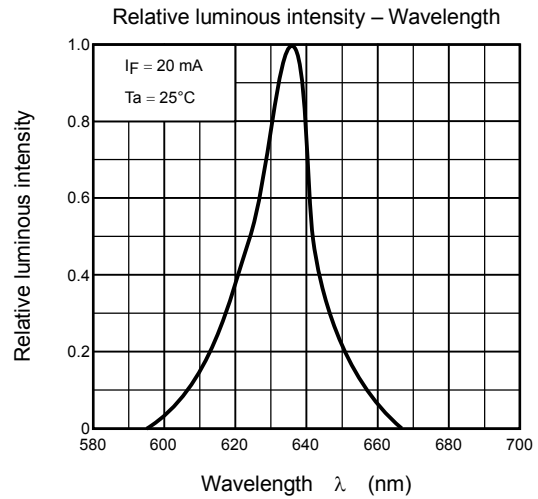
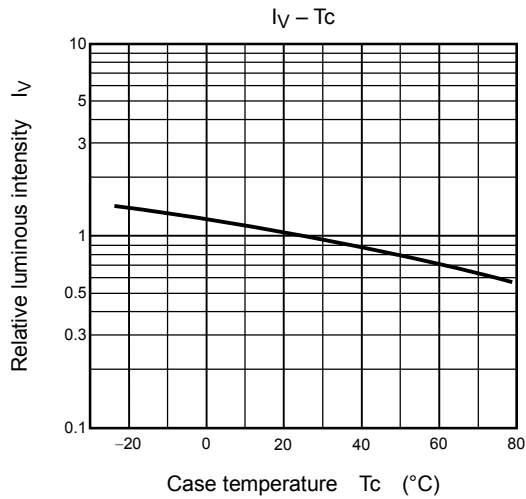
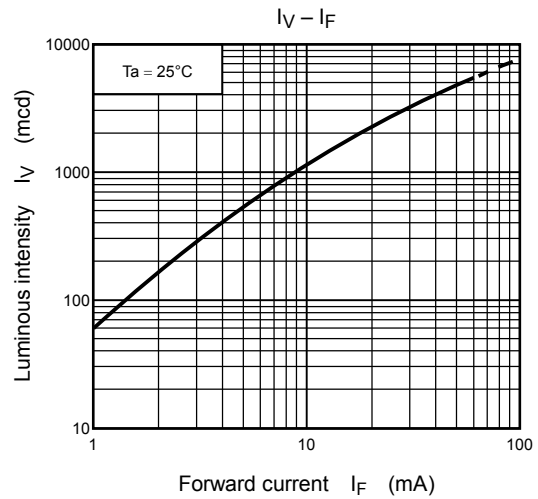
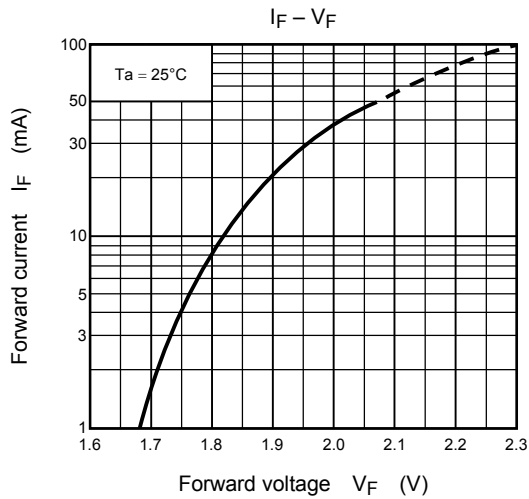
Please be careful of the following:

- Soldering temperature: 260°C max, soldering time: 3 s max
(soldering portion of lead: up to 2 mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5 mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.
- This visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by this IR light.

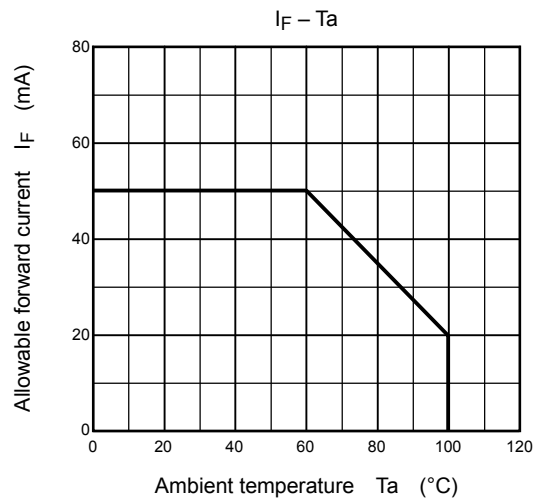
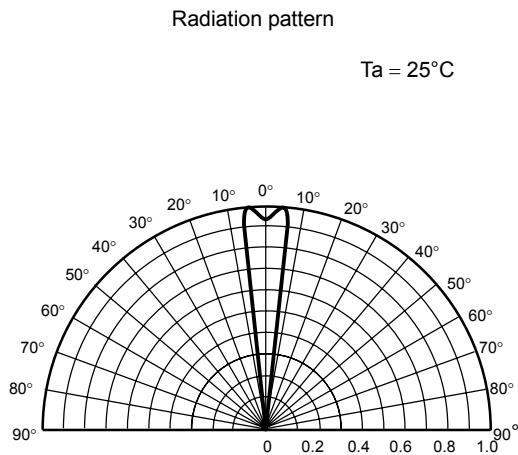
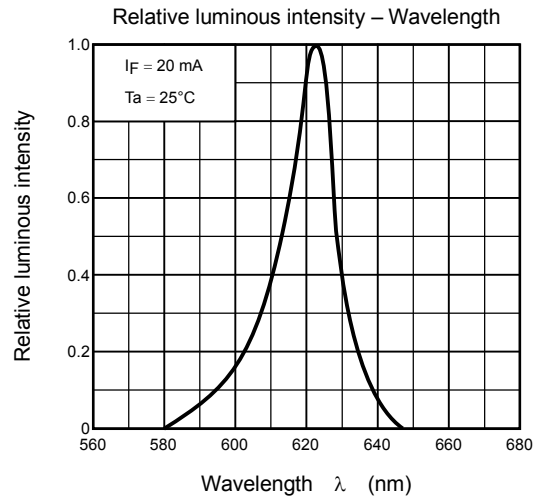
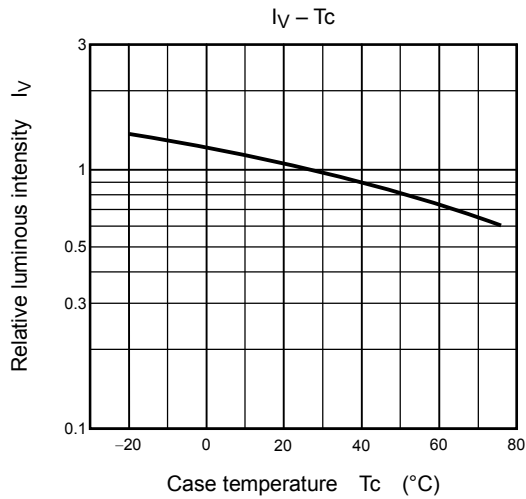
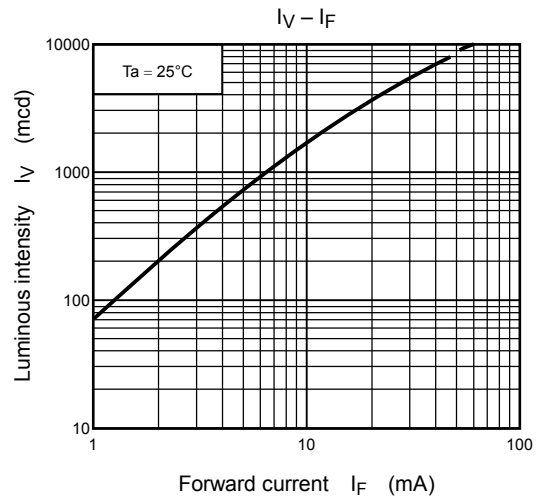
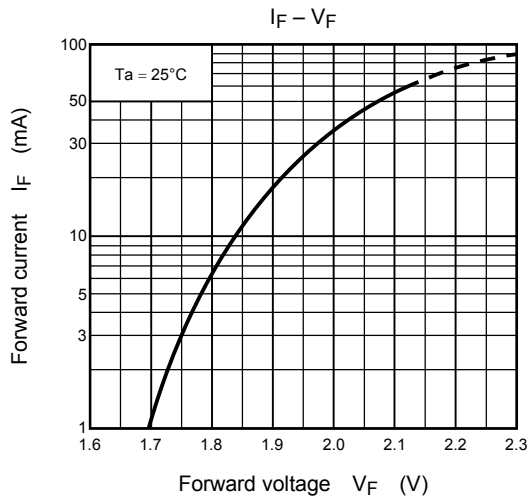
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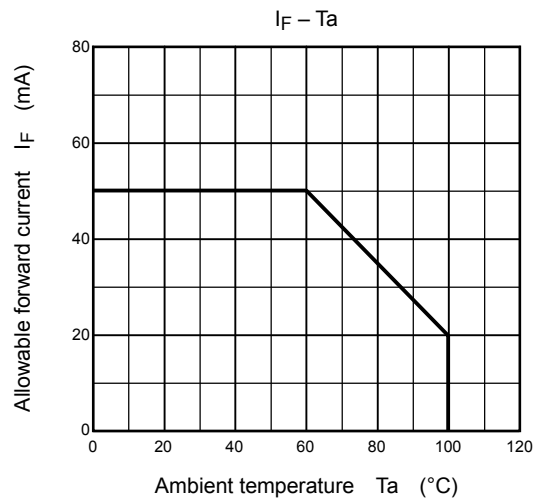
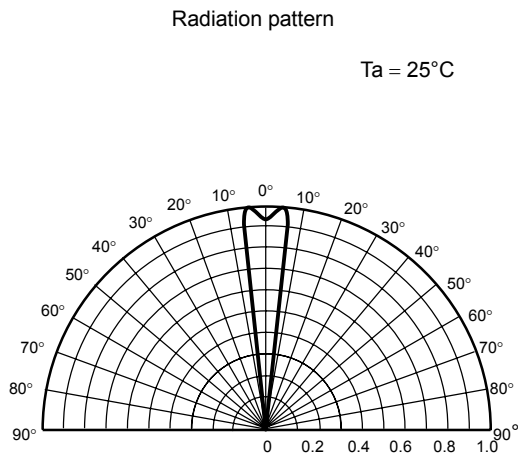
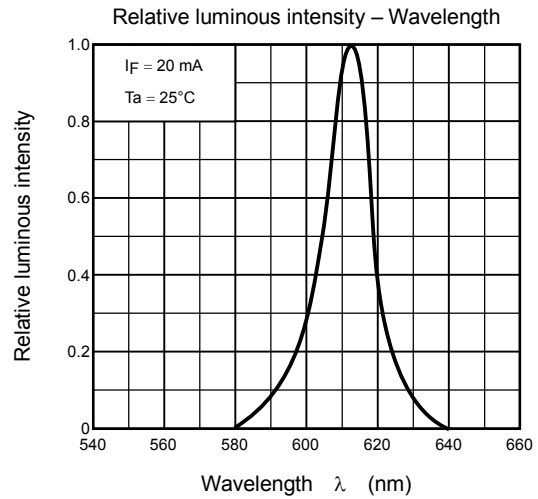
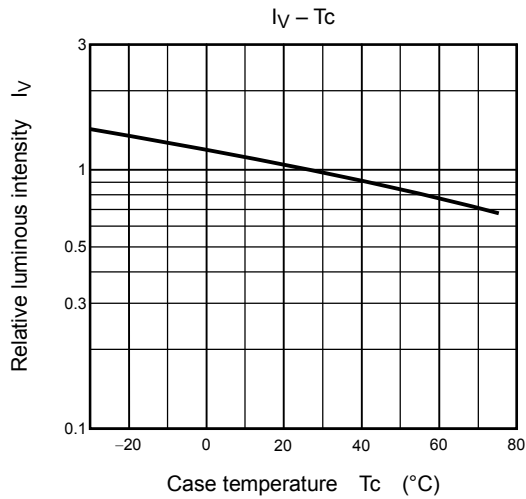
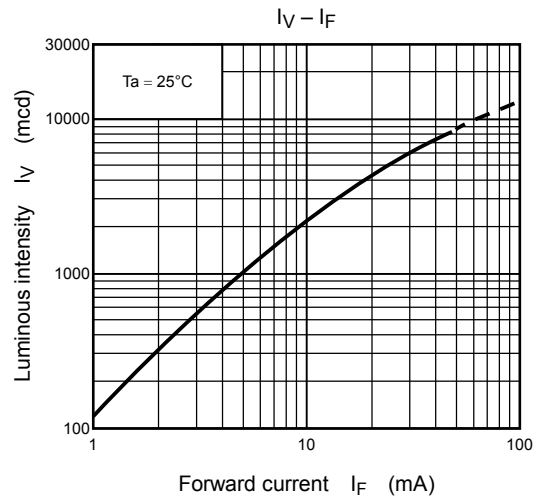
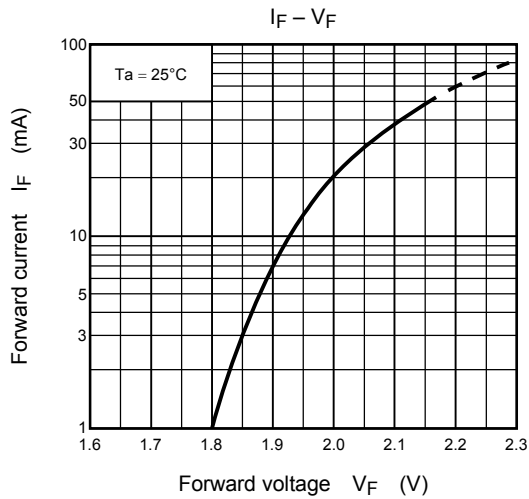
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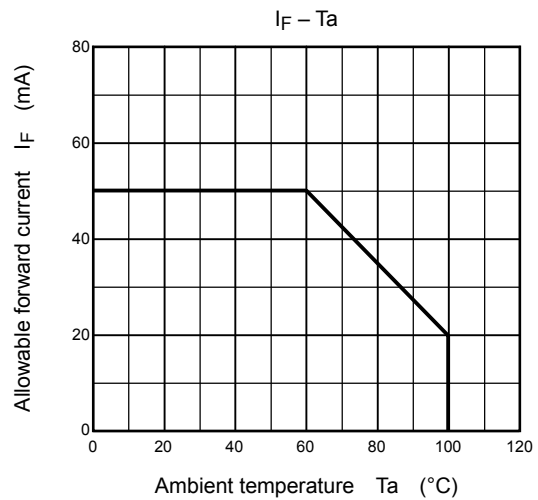
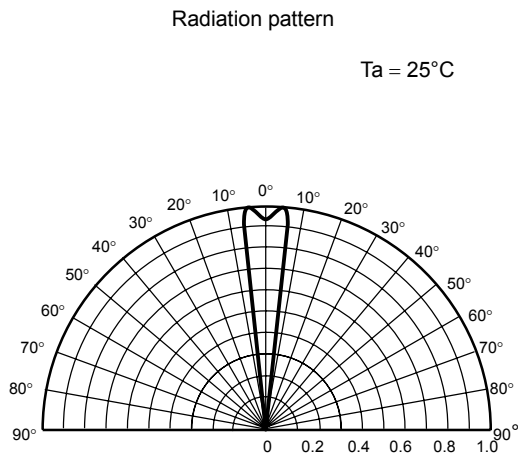
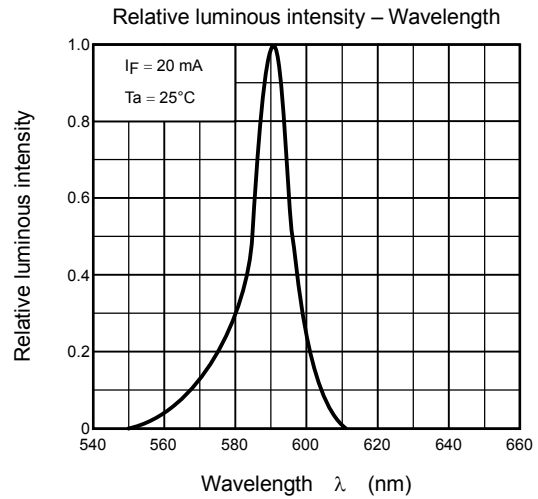
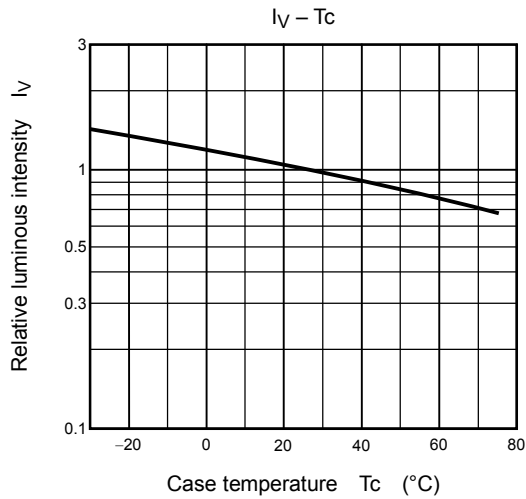
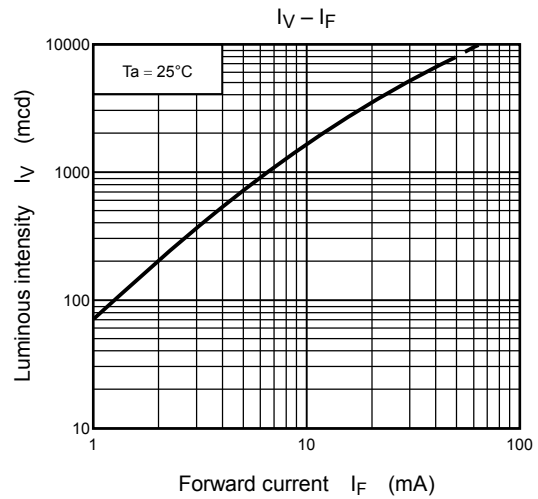
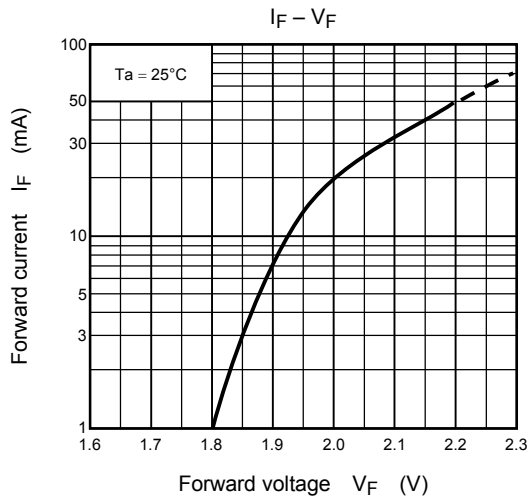
TLSE50T



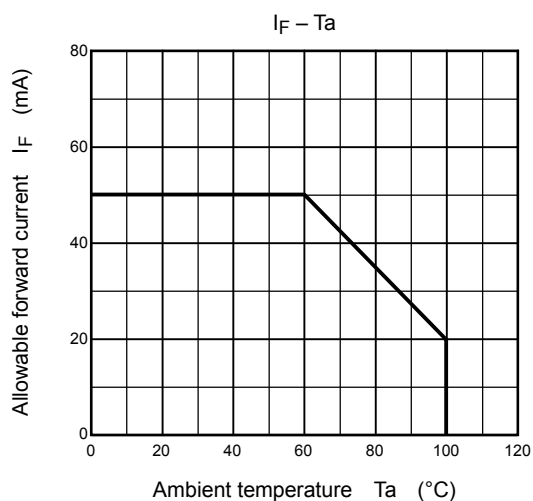
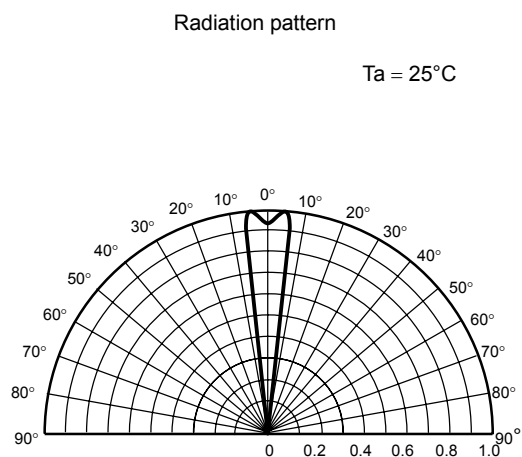
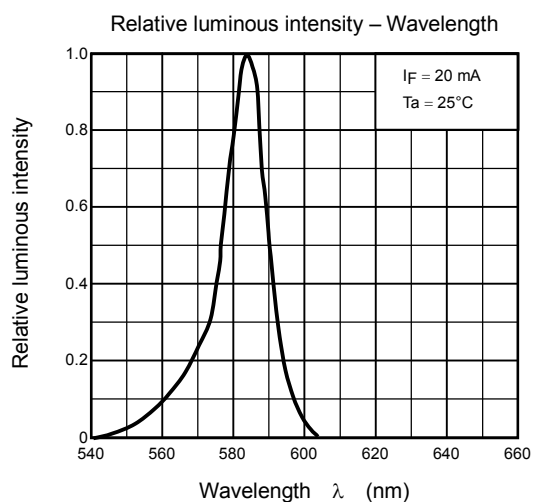
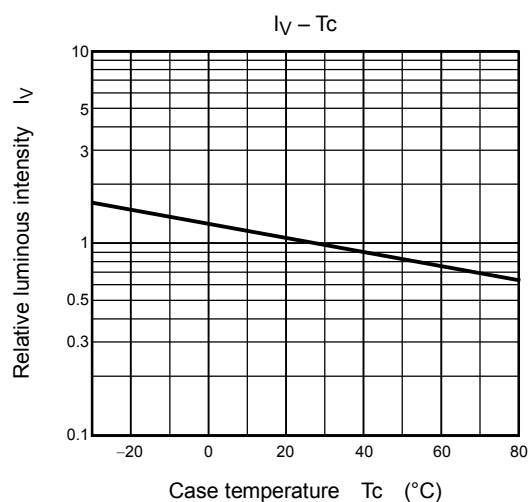
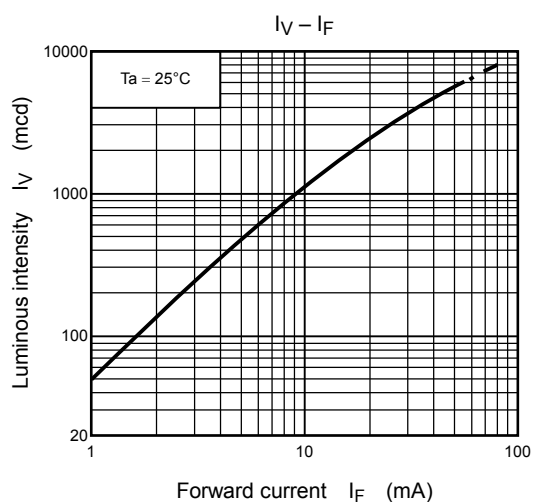
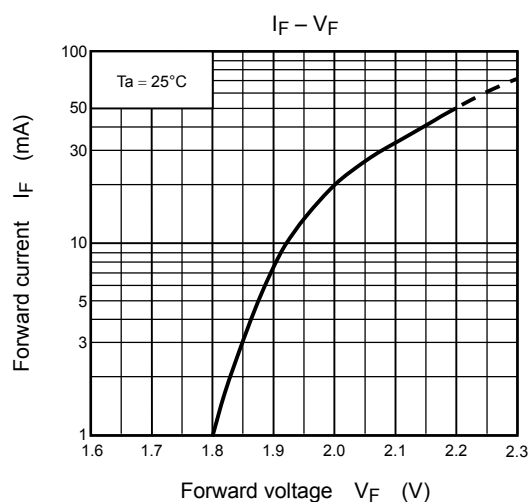
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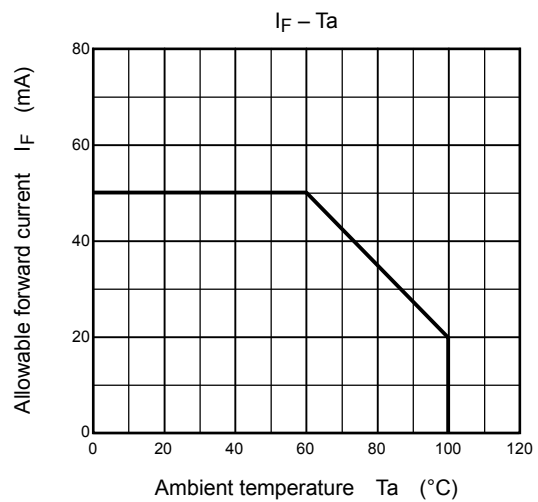
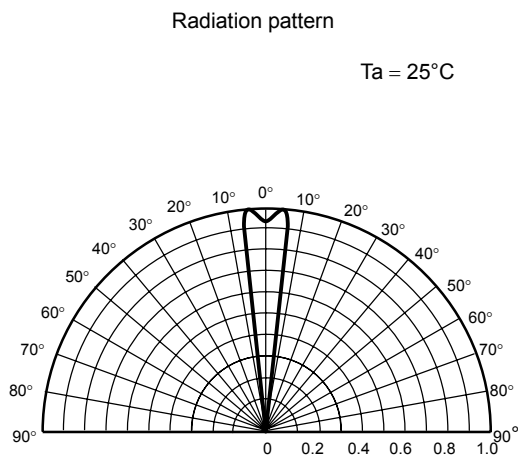
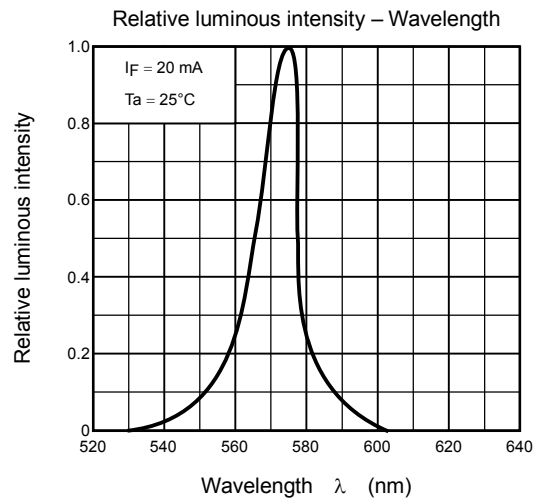
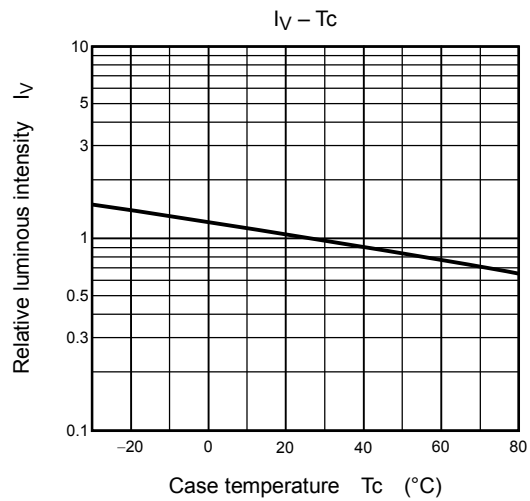
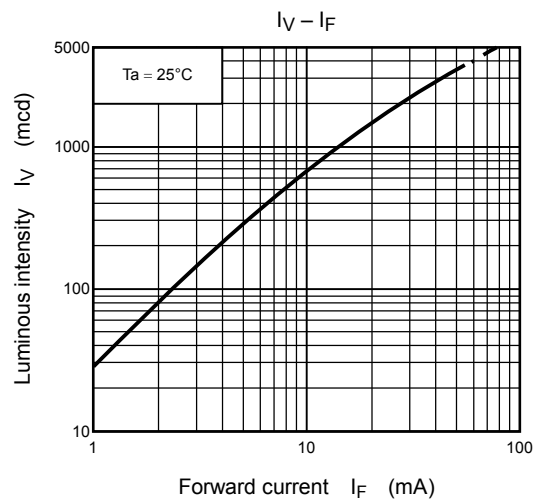
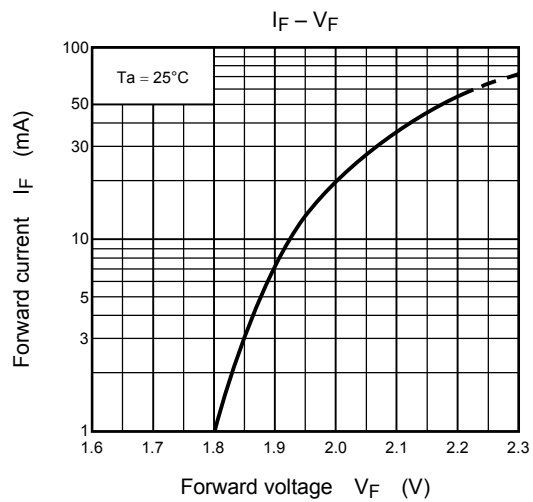
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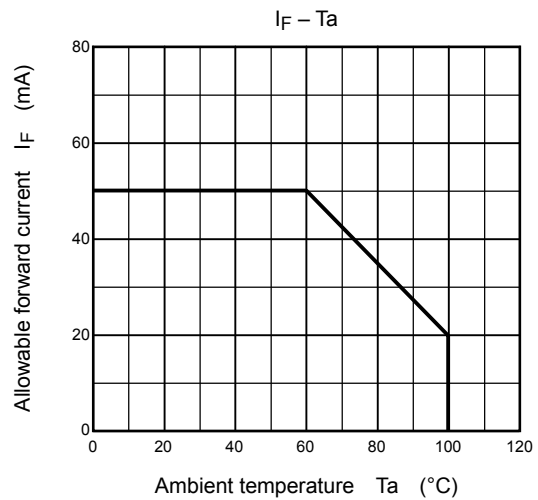
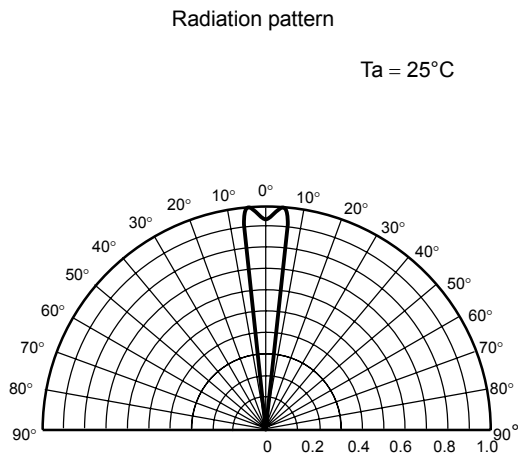
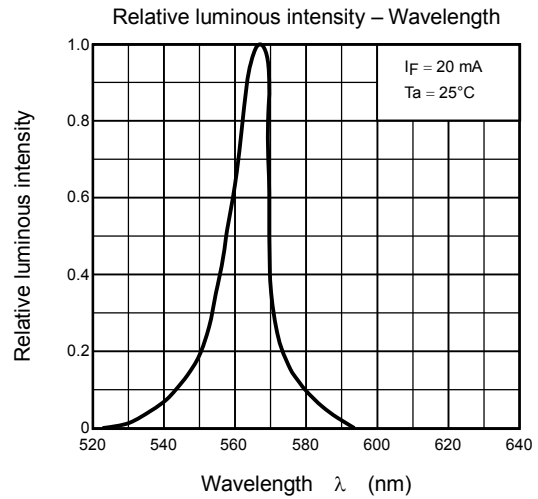
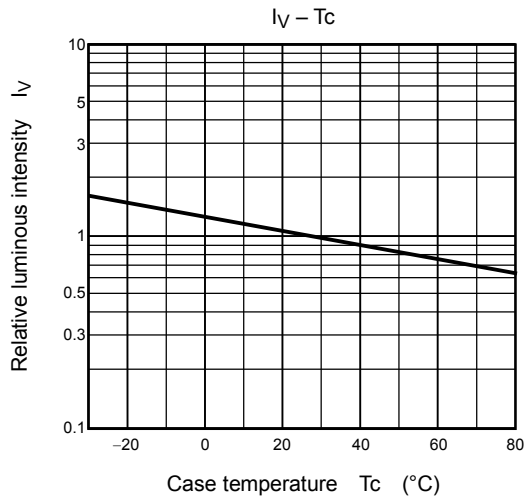
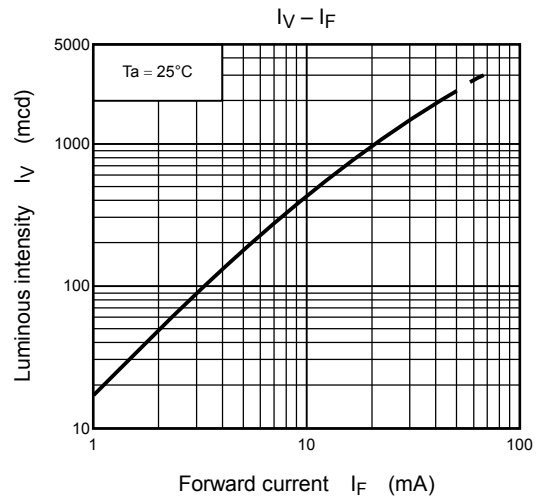
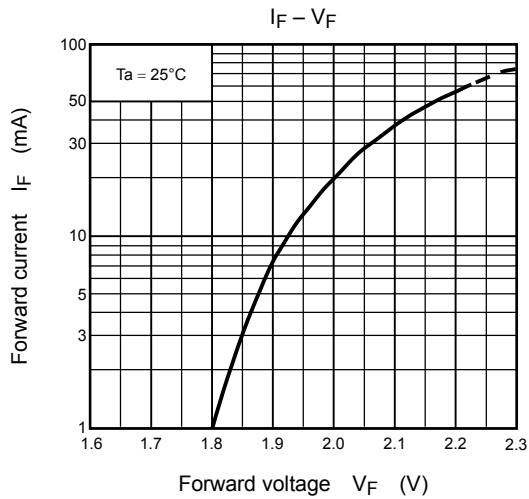
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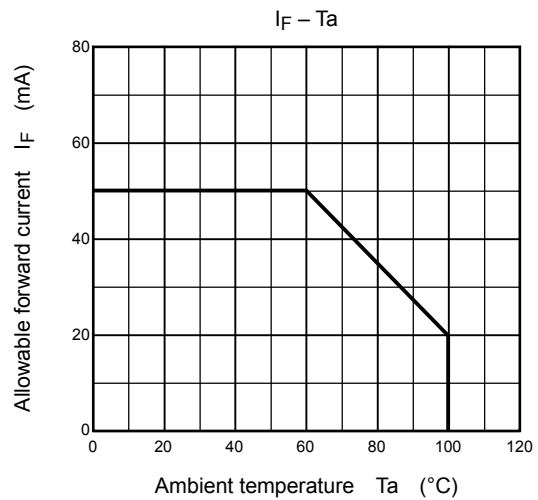
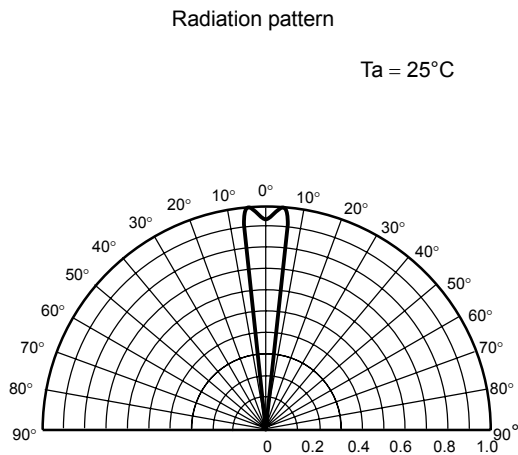
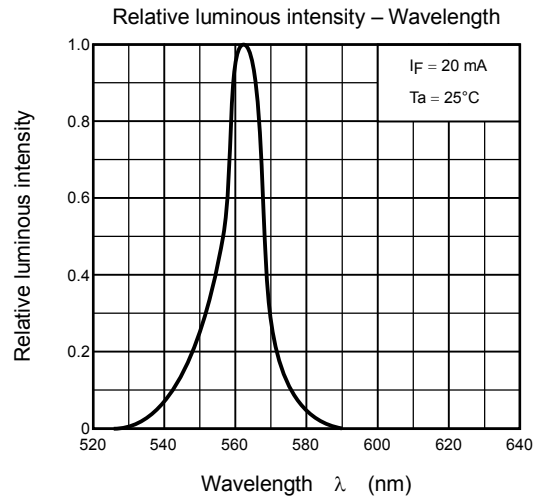
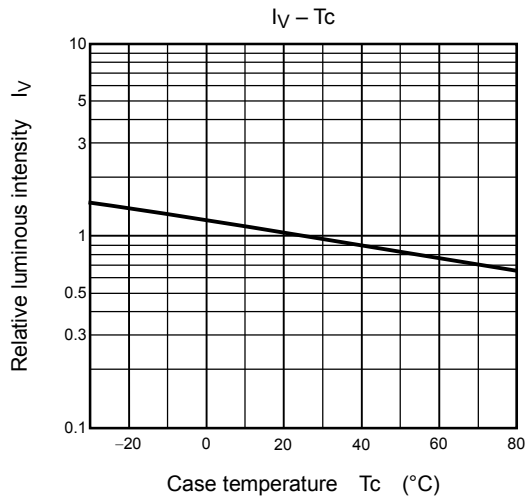
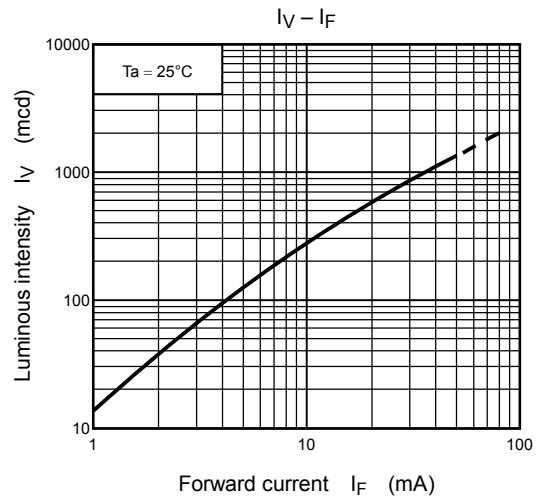
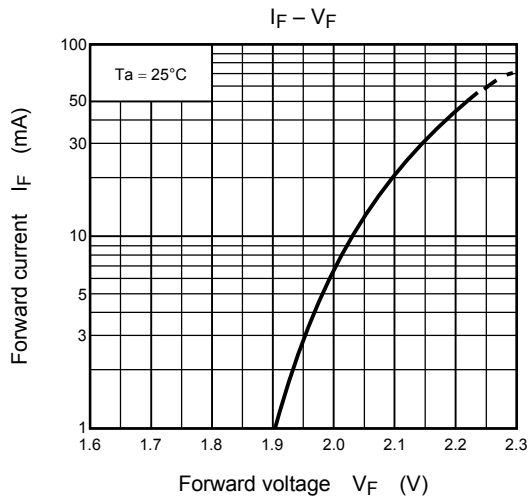
TLGE50T



TLFGE50T



TLPGE50T



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